Audio Jack Detection and Configuration Switch

The FSA8008A is an audio jack detector and switch for 3– or 4–pole accessories. In addition to detection, the FSA8008A features an integrated MIC switch that allows the processor to configure the audio jack. The architecture is designed to allow common third–party headphones to be used for listening to music from mobile handsets, personal media players, and portable peripheral devices.

Features

- Determines 3– or 4–Pole Audio Jacks
- Removes Audio Jack Pop-n-Click Caused by MIC Bias
- Detects Audio Jack Accessories:
 - Standard Headphones
 - Headsets with MIC
 - Send / End Button Presses
- Integrates a MIC Switch for 4–Pole Configuration

Applications

- 3.5 mm and 2.5 mm Audio Jacks
- Cellular Phones, Smartphones
- MP3 and PMP

Related Resources

• FSA8008A Demonstration Board



ON Semiconductor®

www.onsemi.com



Detection	Accessory Plug–In 3– or 4–Pole Audio Jack Send/End Key Pressed
Functionality	Decreased Timing for Sensitive Send/End Keys
Switch Type	MIC
V _{DD}	2.5 to 4.4 V
V _{IO}	1.6 to V _{DD}
THD (MIC)	0.01% Typical
ESD (Air Gap)	15 kV
Operating Temperature	–40°C to 85°C
Package	10–Lead UMLP 1.4 x 1.8 x 0.5 mm, 0.4 mm Pitch
Top Mark	KD
Ordering Information	FSA8008AUMX

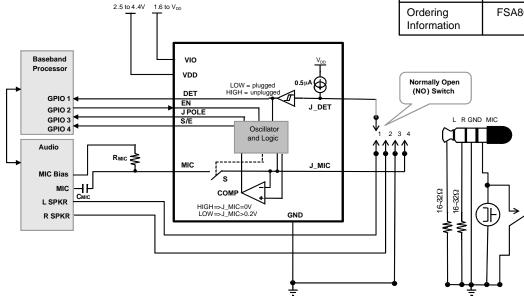


Figure 1. Mobile Phone Example

Pin Configuration

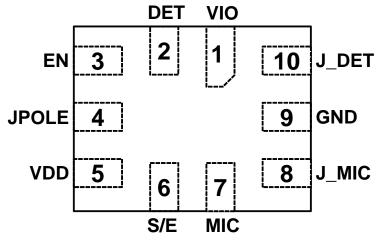
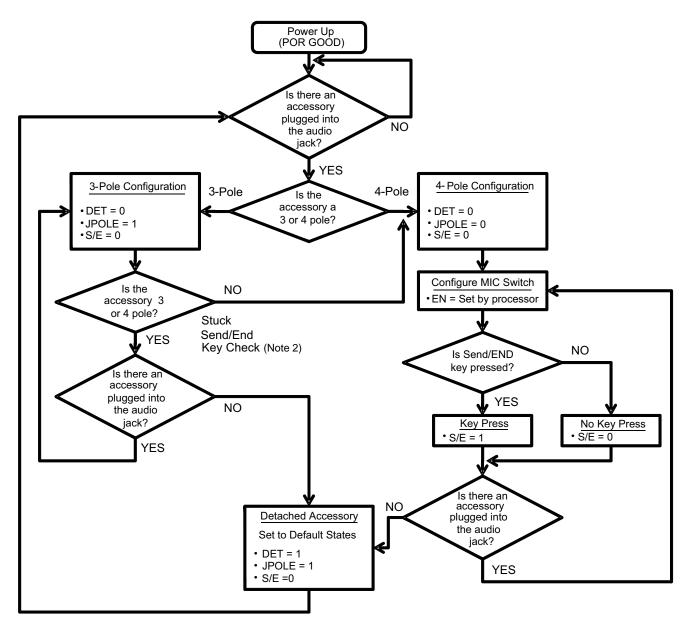


Figure 2. 10-Lead UMLP Pin Assignment (Through View)

Table 1. PIN DESCRIPTIONS

Name	Pin #	Туре	Description		Function			
DET	DET 2	Output		0	Plugged			
	on the J_DET pin	1	Unplugged					
JPOLE	4	Output	Indicates if an accessory plugged into the audio jack is 3 pole or 4	0	4-pole jack			
			pole	1	3-pole jack			
S/E	S/E 6 Output		Indicates state of SEND/END for a 4-pole accessory when a key	0	No key press			
	has been pressed		Key press					
EN 3 Input	Input		0	MIC / J_MIC switch open				
			pins	1	MIC / J_MIC switch closed			
J_DET			nput from a pin of the audio jack socket tied to a mechanical switch		Plugged			
			that typically closes whenever an audio jack is inserted into that socket		Unplugged			
MIC	7	Switch	Microphone switch path that goes to the microphone preamplifier	See EN pin				
J_MIC	8	Switch	Microphone switch path that connects to the microphone and SEND/ END key audio jack pole					
VDD	5	Power	Core supply voltage					
VIO	1	Power	Baseband I/O supply voltage					
GND	9	Ground	Ground for both the audio jack and the PCB					

1. $0 = V_{OL}$ or V_{IL} ; $1 = V_{OH}$ or V_{IH}





2. Stuck Send/End key function is only available if EN=H.

Table 2. STUCK SEND/END KEY

EN	FSA8008A
н	Stuck Send / End Key Active
L	Stuck Send / End Key Disabled

Table 3. STATES DURING POWER GOOD AND OFF

State Description	VDD	VIO	DET	EN	JPOLE	S/E	J-DET	MIC Switch		
Active	1	1	Active							
OFF	0	0	1 (uppluggod)	3-State	1 (2 Dala)	0 (No Droco)	H (uppluggod)	Open		
	1	0	(unplugged)		(3 Pole)	(No Press)	(unplugged)			
	0	1								

			S/E		JPO		
J_DET	J_MIC	EN	3 Pole	4 Pole	3 Pole	4 Pole	DET
0	1	1	0 (no press)	0 (no press)	0 (4 Pole)	0 (4 Pole)	0
0	0	0	0 (no press)	1 (press)	1 (3 Pole)	0 (4 Pole)	0
0	1	0	0 (no press)	0 (no press)	1 (3 Pole)	0 (4 Pole)	0
0	0	1	0 (no press)	1 (press)	1 (3 Pole)	0 (4 Pole)	0
1	Х	Х	0 (no press)	0 (no press)	1 (3 Pole)	1 (3 Pole)	1

Table 4. I/O STATES DURING DETECTION (Note 3)

3. State detected after initial plug-in.

Table 5. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Units
V _{DD} & V _{IO}	Supply Voltage from Battery		-0.5	6.0	V
V _{SW}	Switch I/O Voltage for "S" Switch and All Input Volt	ages Except J_DET	-0.5	V _{DD} +0.5	V
V_{JD}	Input Voltage for J_DET Input		-1.5	V _{DD} +0.5	V
I _{IK}	Input Clamp Diode Current				mA
I _{SW}	Switch I/O Current (Continuous)			50	mA
T _{STG}	Storage Temperature Range			+150	°C
Τ _J	Maximum Junction Temperature			+150	°C
ΤL	Lead Temperature (Soldering, 10 Seconds)			+260	°C
ESD	IEC 61000-4-2 System ESD	Air Gap	15.0		kV
		Contact	8.0		
	JEDEC JESD22-A114, Human Body Model	All Pins	7.5		
		J_DET, J_MIC, V _{DD} , V _{IO}	12.0		
	JEDEC JESD22-C101, Charged Device Model	All Pins	2.0		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.4. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Table 6. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{DD}	Battery Supply Voltage	2.5	4.4	V
V _{IO}	Parallel I/O Supply Voltage	1.6	V _{DD}	V
T _A	Operating Temperature	-40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

	Parameter	V _{DD} (V)		T _A =	Τ		
Symbol			Conditions	Min	Тур	Max	Units
MIC SWITCH					-		-
R _{ON}	Mic Switch On Resistance	2.5	$I_{OUT} = 30 \text{ mA},$		0.9	2.9	Ω
		2.8	V _{IN} = 2.0 V		0.8	2.5	
		3.8			0.6	2.0	1
R _{FLAT(ON)}	On Resistance Flatness	2.5	I _{OUT} = 30 mA, V _{IN} = 1.6, 2.0, 2.5		1.50		
		2.8	$I_{OUT} = 30 \text{ mA},$		0.70		
		3.8	V _{IN} = 1.6, 2.0, 2.8		0.25		1
V _{IN}	Switch Input Voltage Range	2.5 to 4.4		0		V _{DD}	V
C _{ON}	MIC and J_MIC Switch ON Capaci- tance	3.8	f = 1 MHz		76		pF
C _{OFF}	MIC and J_MIC Switch OFF Capaci- tance	3.8	f = 1 MHz		24		pF
J_DET							
$J_\text{DET}_{\text{AudioV}}$	Audio Voltage Range on J_DET Pin	2.5 to 4.4	DET = L	-1		1	V
J_DET _{Audiof}	Audio Frequency on J_DET Pin	2.5 to 4.4	DET = L	20		20000	Hz
J_DET _{RGND}	Detection Resistance to Ground	2.5 to 4.4	Audio Jack Inserted	0		500	KΩ
J_DET_{HYS}	Hysteresis of J_DET				100		mV
PARALLEL I/C	0						
V _{IH}	Input High Voltage			0.7 x V _{IO}		V _{IO}	V
V _{IL}	Input Low Voltage					0.3 x V _{IO}	V
V _{OH}	Output High Voltage	I _{OH} = –100 μA		0.8 x V _{IO}			V
V _{OL}	Output Low Voltage	I _{OL} = +100 μA				0.2 x V _{IO}	V
COMPARATO	R						
V _{COMP}	Comparator Threshold for SEND/ END Sensing	2.5–3.8	J_DET, EN = L		200		mV
CURRENT							
I _{OFF}	Power Off Leakage Current Through Switch	0	MIC and J_MIC Ports V_{IN} = 4.4 V			1.5	μΑ
I _{IN}	Input Leakage Current	0 to 4.4	Inputs 0 = 4.4 V			1	μΑ
I _{CC-SLNA}	Battery Supply Sleep Mode Current No Accessory Attached	2.5 to 4.4	Static Current During Sleep Mode (EN = L)		1	3	μΑ
I _{CC-SLWA}	Battery Supply Sleep Mode Current with Accessory Attached	2.5 to 4.4	Active Current (EN = L and/or DET = H)		15	25	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 8. AC ELECTRICAL CHARACTERISTICS All typical values are for V_{CC} = 3.3 V at T_A = 25°C unless otherwise specified.

				T _A = −40 to +85°C			
Symbol	Parameter	V _{DD} (V)	Conditions	Min	Тур	Max	Unit
MIC SWITCH							
THD	Total Harmonic Distortion	3.8	$\begin{array}{l} R_{T} = 600 \; \Omega, \; V_{SW} = 0.5 \; V_{PP}, \\ f = 20 \; Hz \; to \; 20 \; kHz, \; V_{IN} = 2.0 \; V \end{array}$		0.01		%
O _{IRR}	Off Isolation	3.8	f = 20 kHz, R _S = 32 Ω, C _L = 0 pF, R _T = 32 Ω		-90		dB

PARALLEL I/O

t _R , t _F	Output Edge Rates	2.5	C _L = 5 pF, 20% to 80%	19	ns
	(DET, S/E, JPOLE)	3.8		15	
^t POLL	On Time of MIC Switch for Sensing SEND/END Button Press Oscillator Stable Time	2.5 to 4.4		1	ms
t _{PER}	Period of MIC Switching Time for Sensing SEND/END Button Press	2.5 to 4.4		10	
t _{DET-IN}	Debounce Time after J–DET Changes State from High to Low	2.5 to 4.4		422	ms
^t DET_REM	Debounce Time after J_DET Changes State from Low to High	2.5 to 4.4		30	μs
^t DET	Detection Timeout for Sensing 3–Pole or 4–Pole Audio Jack Plugged In	2.5 to 4.4		4.5	ms
t _{KBK}	Debounce Time for Sensing SEND/END Key Press / Release	2.5 to 4.4		27	ms

POWER

PSRR Power Supply Rejection Ratio	3.8	Power Supply Noise 300 mV _{PP} , Measured 10/90%, f = 217 Hz		-90		dB	1
-----------------------------------	-----	--	--	-----	--	----	---

ORDERING INFORMATION

Part Number	Operating Temperature Range	Top Mark	Package
FSA8008AUMX	−40 to +85°C	KD	10–Lead, 1.4 x 1.8 x 0.55 mm, 0.4 mm Pitch, Ultrathin Molded Leadless Package (UMLP)

UQFN10 1.4x1.8, 0.4P CASE 523BC ISSUE O				
PIN#1 IDENT -	DATE 31 OCT 2016			
SIDE VIEW $0.40\pm.05$ $(9X)$ 3 $-1.40\pm.05$ (0.20)4X DETAIL A				
0.40±.05 DETAIL A SCALE : 2X PACKAGE EDGE LEAD OPTION 1 SCALE : 2X LEAD OPTION 2 SCALE : 2X SCALE : 2X	 NOTES: A. PACKAGE DOES NOT CONFORM TO ANY JEDEC STANDARD. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009. D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN. 			
DOCUMENT NUMBER: 98AON13705G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION: UQFN10 1.4x1.8, 0.4P PAGE 1 OF 1				
ON Semiconductor and ()) are trademarks of Semiconductor Components Indus	tries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries.			

ON Semiconductor and unarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor date sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use a a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor houteds for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

Email Requests to: orderlit@onsemi.com

North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910 Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative